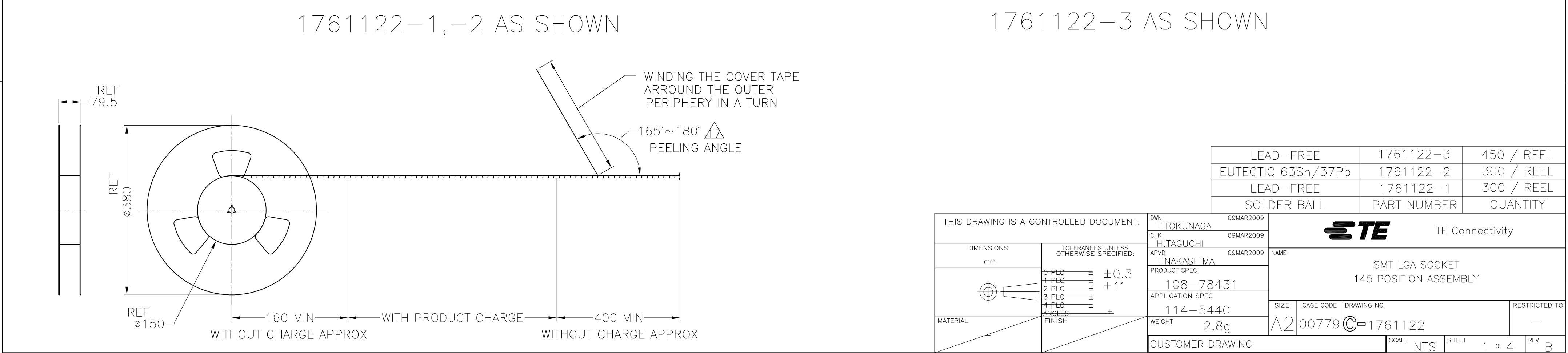
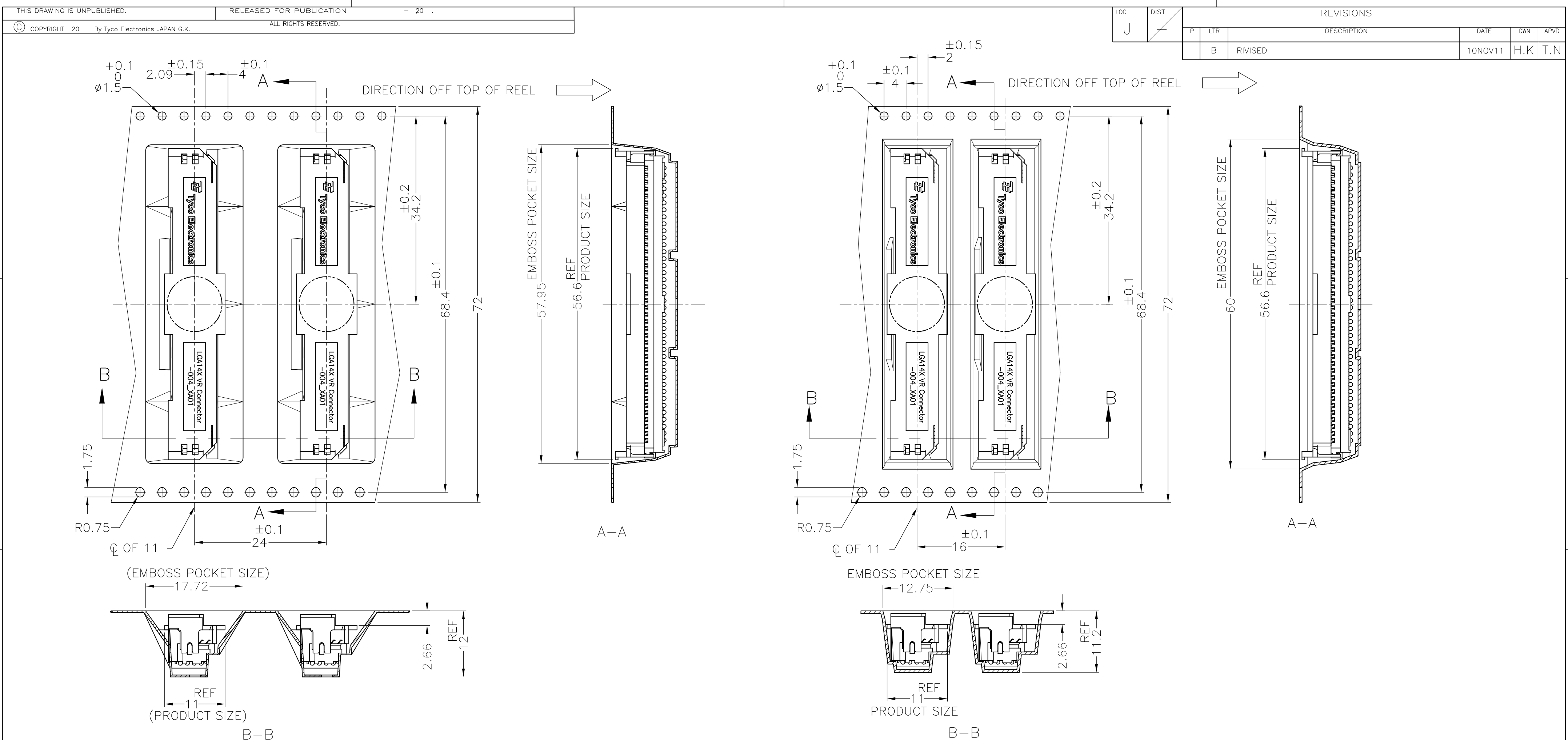
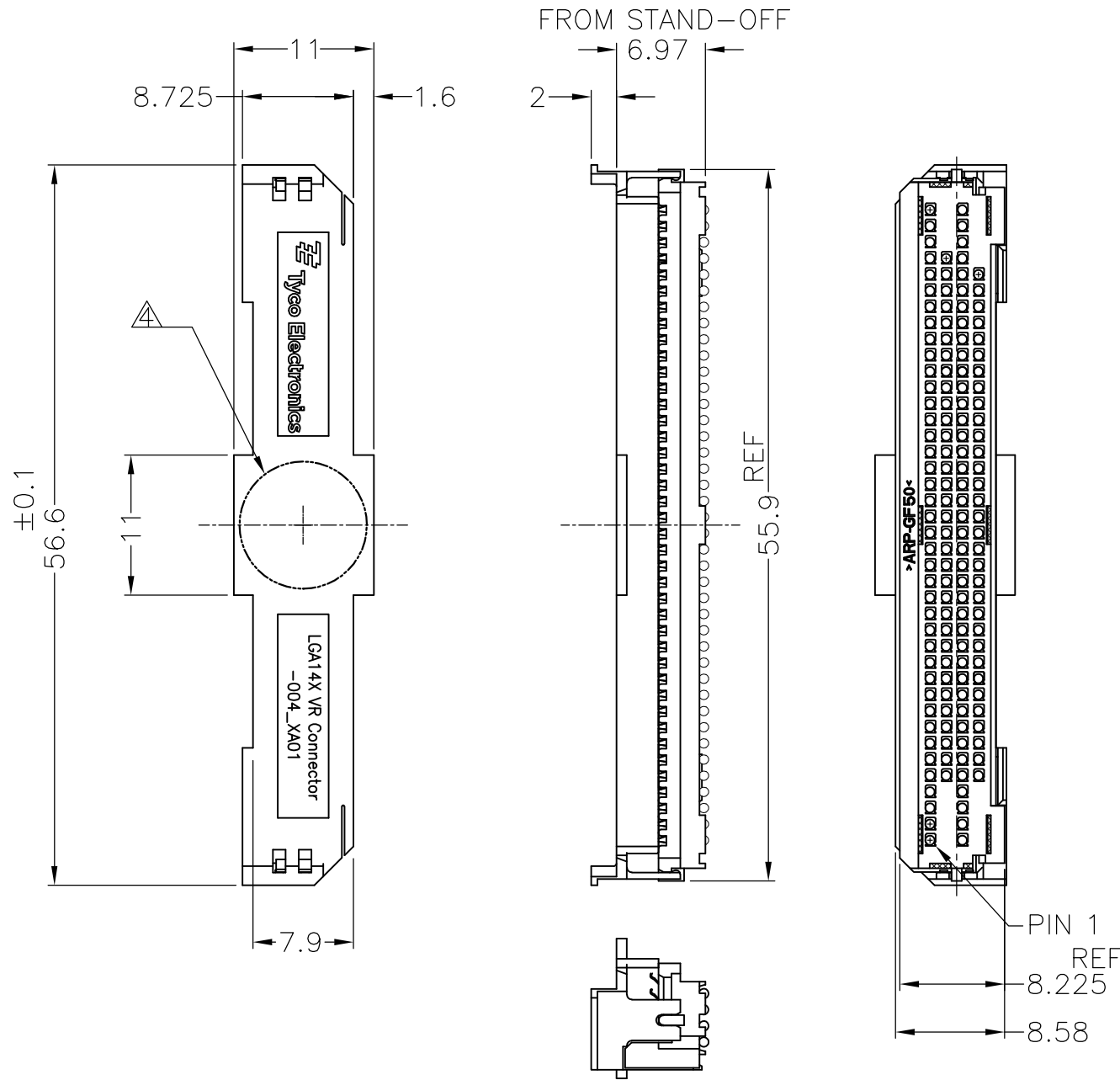




LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
J	—		—	SEE SHEET 1	—	—	—



INDIVIDUAL PIECE
VIEWS WITH PnP COVER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DWN

CHK

APVD

PRODUCT SPEC

APPLICATION SPEC

WEIGHT

CUSTOMER DRAWING

DIMENSIONS:

mm

TOLERANCES UNLESS OTHERWISE SPECIFIED:

0 PLC $\pm$

1 PLC $\pm$

2 PLC $\pm$

3 PLC $\pm$

4 PLC $\pm$

ANGLES $\pm$

FINISH

± 0.3

$\pm 1^\circ$

$\pm$

NAME

SMT LGA SOCKET
145 POSITION ASSEMBLY

SIZE

A2

CAGE CODE

00779

DRAWING NO

C=1761122

RESTRICTED TO

-

SCALE

NTS

SHEET

2 of 4

REV

B

TE Connectivity

TE

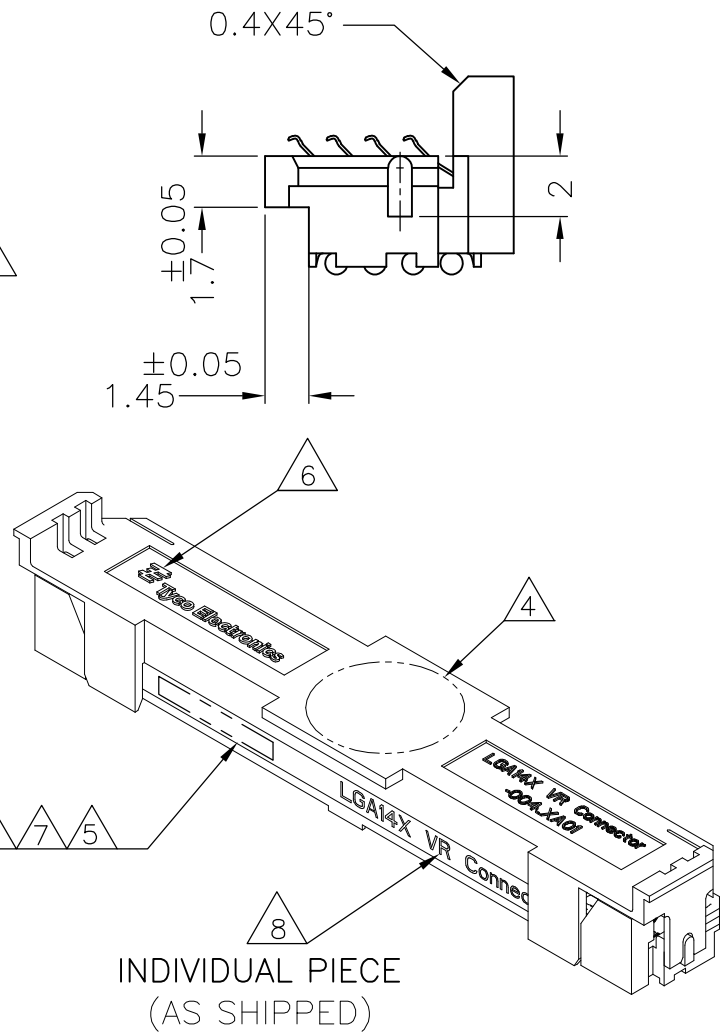
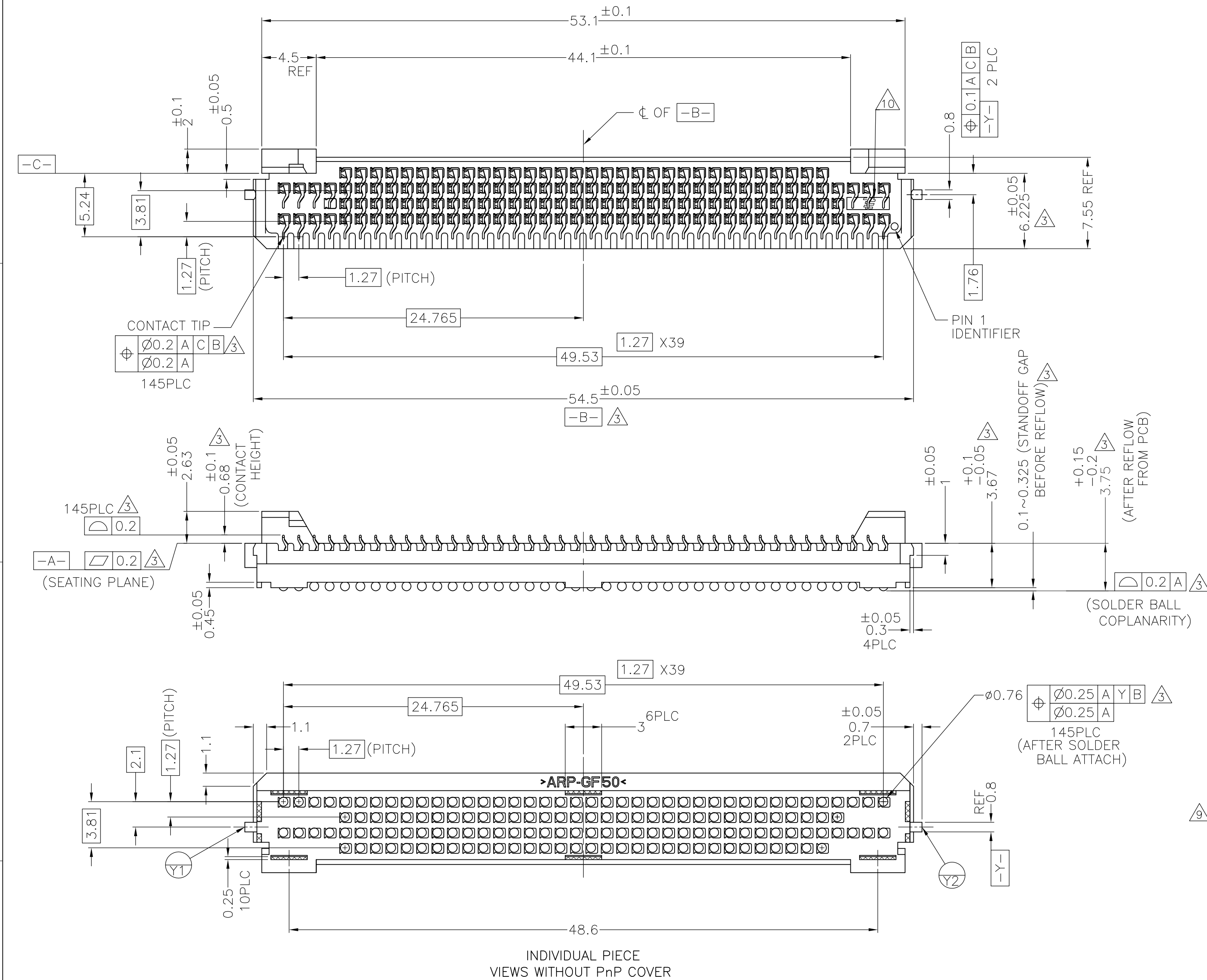
1471-9 (3/11)

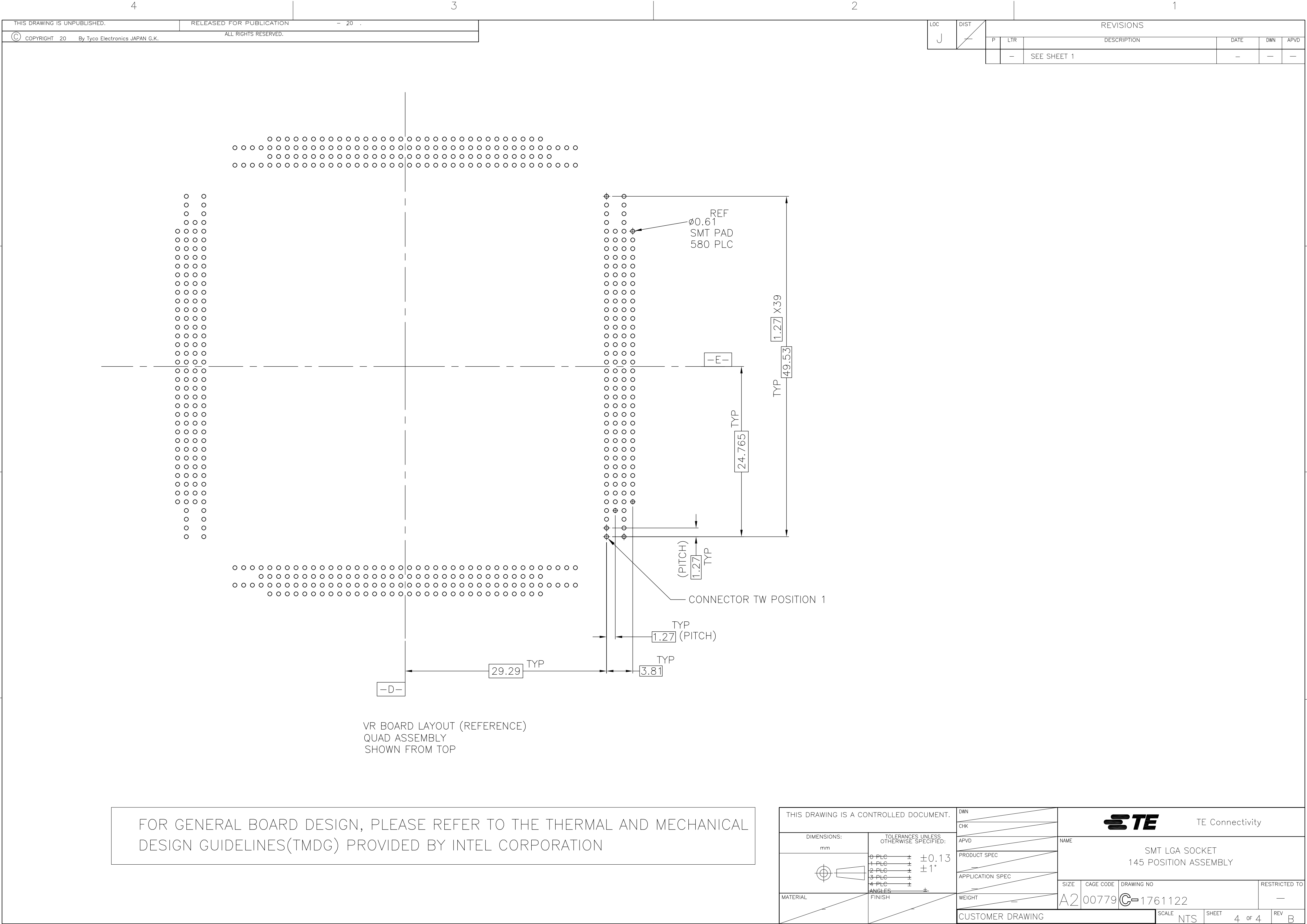
1761122

LOC J	DIST —	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
			—	SEE SHEET 1	—	—	—

- 1 MATERIAL:
HOUSING : HIGH TEMPERATURE THERMOPLASTIC, UL 94V-0
CONTACT : COPPER ALLOY
SOLDER BALLS : SEE TABLE
- 2 FINISH:
CONTACT : 0.76μm MIN GOLD OVER 1.27μm MIN NICKEL
IN CONTACT MATING ZONE

- 3 CTF DIMENSIONS
- 4 AREA TO SUPPORT THE VACUUM TYPE PICK AND PLACE
HIGH VOLUME MANUFACTURING SYSTEM
- 5 LOT NUMBER INDICATED IN THIS AREA.
- 6 TE LOGO INDICATED IN THIS AREA.
- 7 SOLDER BALL TYPE INDICATED IN THIS AREA
"LF" TEXT FOR LEAD FREE SOLDER
NO TEXT FOR TIN-LEAD SOLDER.
- 8 PRODUCT ID INDICATED IN THIS AREA
- 9 INTEL CONCEPT BOM NUMBER INDICATED IN THIS AREA





FOR GENERAL BOARD DESIGN, PLEASE REFER TO THE THERMAL AND MECHANICAL DESIGN GUIDELINES(TMDG) PROVIDED BY INTEL CORPORATION

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:

mm

TOLERANCES UNLESS OTHERWISE SPECIFIED:

Ø PLC	±	±0.13
1 PLC	±	±1°
2 PLC	±	
3 PLC	±	
4 PLC	±	
ANGLES	±	
FINISH		

MATERIAL

DWN

CHK

APVD

PRODUCT SPEC

APPLICATION SPEC

WEIGHT

CUSTOMER DRAWING

TE Connectivity

NAME

SMT LGA SOCKET
145 POSITION ASSEMBLY

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RESTRICTED TO

-

SCALE

NTS

SHEET

4 OF 4

REV

B